## **CLAIMS**

- 1. A semiconductor device comprising
- a first semiconductor comprising a substrate, and a semiconductor chip disposed on the major surface of said substrate and sealed with a resin;

a wiring board,

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spacers disposed between said wiring board and said substrate and connecting said first semiconductor to said wiring board electrically; and

a second semiconductor electrically connected to said wiring board and disposed in the space formed by said wiring board, said substrate, and said spacer.

- 15 2. The semiconductor device according to claim 1, wherein a plurality of said semiconductors are disposed on said wiring board.
  - 3. A method for manufacturing a semiconductor device comprising the steps of:
- 20 mounting a first semiconductor on the respective spacers of a spacer substrate formed by the sequence of a plurality of spacers for a semiconductor device;

mounting a second semiconductor on the opposite sides of the portions of said respective spacers whereon said first spacer has been connected, and in the same direction of said first semiconductor, respectively; and

splitting said spacer substrate for each of said semiconductor devices.